



55V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C
55V	$12m\Omega @ V_{GS} = 10V$	80A
55 V	$18m\Omega @ V_{GS} = 4.5V$	65A

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Power Supplies
- Motor Control
- DC-DC Converters

Features

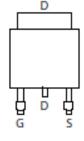
- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching Ensures more Reliable and Robust End Application
- Low On-Resistance
- Low Input Capacitance
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Data Sheet (<u>DMNH6011LK3Q</u>)

Mechanical Data

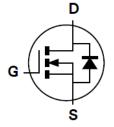
- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Finish Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 ⁽³⁾
- Weight: 0.33 grams (Approximate)



Top View



Pin Out Top View



Equivalent Circuit

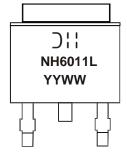
Ordering Information (Note 4)

Part Number	Case	Packaging
DMNH6011LK3-13	TO252 (DPAK)	2,500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



Dil = Manufacturer's Marking
NH6011L = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 18 = 2018)
WW = Week Code (01 to 53)



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V_{DSS}	55	V	
Gate-Source Voltage	V_{GSS}	±12	V	
Continuous Drain Current (Note 7), $V_{GS} = 10V$ $T_C = +25^{\circ}C$ $T_C = +100^{\circ}C$		Ι _D	80 50	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	180	Α	
Maximum Continuous Body Diode Forward Current (Note 7)	I _S	2.8	А	
Avalanche Current, L = 0.1mH (Note 8)	I _{AS}	54	Α	
Avalanche Energy, L = 0.1mH (Note 8)	E _{AS}	147	mJ	

Thermal Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		P_{D}	1.6	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	80	°C/W
Total Power Dissipation (Note 6)		P _D	3.0	W
Thermal Resistance, Junction to Ambient (Note 6) Steady State		$R_{\theta JA}$	42	°C/W
Thermal Resistance, Junction to Case (Note 7)		$R_{\theta JC}$	1.1	C/VV
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

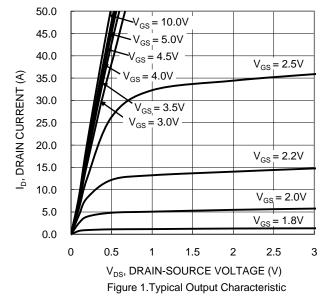
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)	<u>, -</u>				ı	-	
Drain-Source Breakdown Voltage	BV _{DSS}	55	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current, T _J = +25°C	I _{DSS}	_	_	1	μA	$V_{DS} = 55V$, $V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)						•	
Gate Threshold Voltage	V _{GS(TH)}	1	_	2	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
Static Drain-Source On-Resistance	D	_	8.3	12	mΩ	$V_{GS} = 10V, I_D = 25A$	
Static Diam-Source Off-Resistance	R _{DS(ON)}	_	9.0	18	11122	V _{GS} = 4.5V, I _D = 25A	
Diode Forward Voltage	V _{SD}	_	0.7	1.2	V	V _{GS} = 0V, I _S = 1.7A	
DYNAMIC CHARACTERISTICS (Note 10)						•	
Input Capacitance	C _{iss}	_	3,077	_	pF	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	
Output Capacitance	Coss	_	331	_	pF	$V_{DS} = 30V, V_{GS} = 0V,$ f = 1MHz	
Reverse Transfer Capacitance	C _{rss}	_	127	_	pF		
Gate Resistance	R _g	_	1.7	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	23.4	_	nC		
Total Gate Charge (V _{GS} = 10V)	Qg	_	49.1	_	nC	$V_{DS} = 30V, I_{D} = 25A$	
Gate-Source Charge	Q _{gs}	_	5.3	_	nC	V _{DS} = 30V, I _D = 25A	
Gate-Drain Charge	Q_{gd}	_	9.6	_	nC	1	
Turn-On Delay Time	t _{D(ON)}	_	5.9	_	ns		
Turn-On Rise Time	t _R	_	8.7	_	ns	$V_{GS} = 10V, V_{DS} = 30V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	28.2	_	ns	$R_G = 3\Omega$, $I_D = 25A$	
Turn-Off Fall Time	t _F	_	10.2	_	ns		
Body Diode Reverse Recovery Time	t _{RR}	_	30.1	_	ns	I _F = 25A, di/dt = 100A/μs	
Body Diode Reverse Recovery Charge	Q _{RR}	_	25.7	_	nC	I _F = 25A, di/dt = 100A/μs	

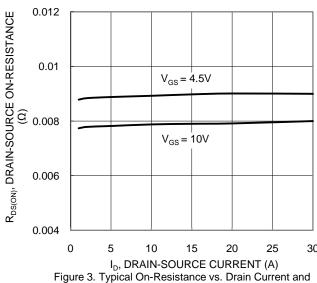
Notes:

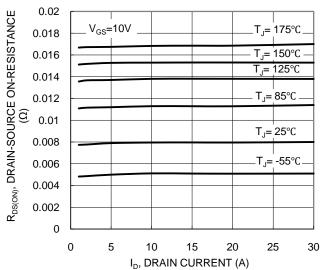
- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- $\label{eq:continuous} \textbf{7. Thermal resistance from junction to soldering point (on the exposed drain pad)}.$
- 8. IAS and EAS ratings are based on low frequency and duty cycles to keep T_J = +25°C.
- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to product testing.





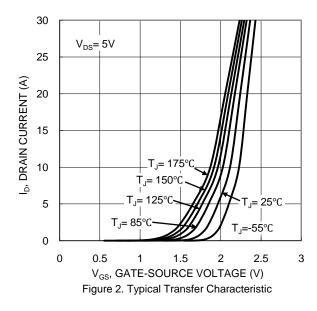


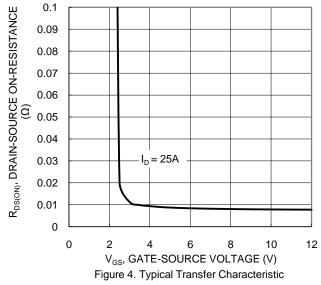




Gate Voltage

Figure 5. Typical On-Resistance vs. Drain Current and Temperature





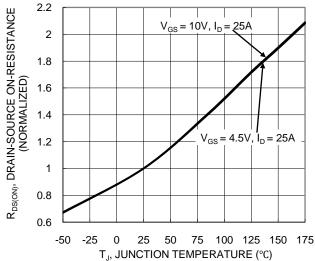


Figure 6. On-Resistance Variation with Temperature





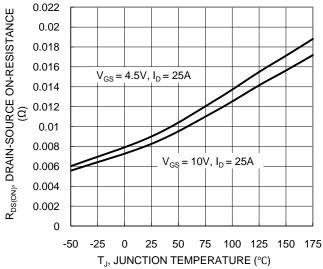
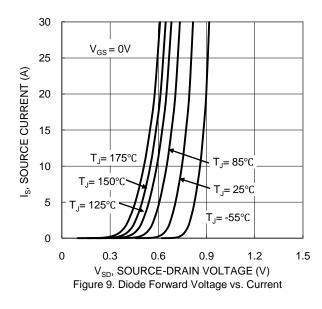
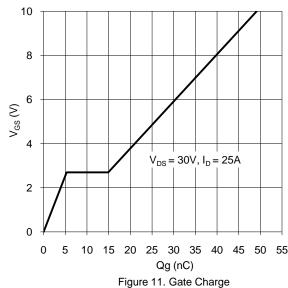


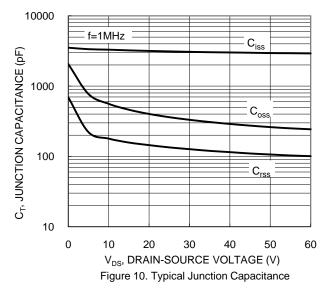
Figure 7. On-Resistance Variation with Temperature

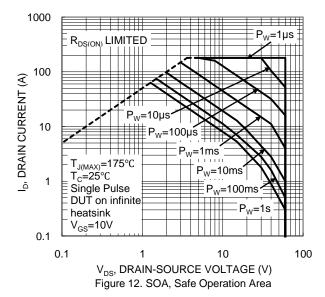




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April 2018

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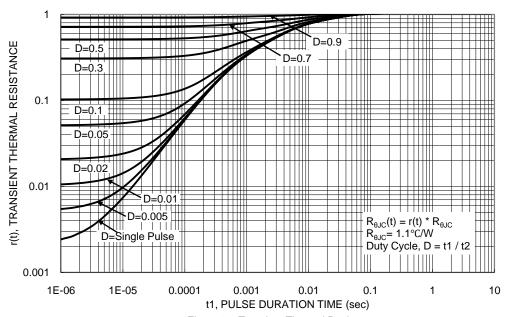
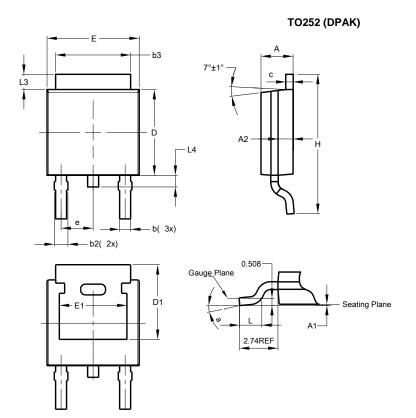


Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

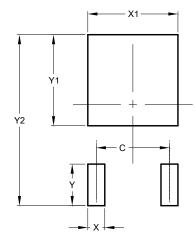


TO252 (DPAK)					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
A1	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
b	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
С	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21	-	-		
е	-	-	2.286		
Е	6.45	6.70	6.58		
E1	4.32	-	-		
Н	9.40	10.41	9.91		
L	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	0.64	1.02	0.83		
а	0°	10°	-		
All	All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK)



Dimensions	Value (in mm)			
С	4.572			
X	1.060			
X1	5.632			
Y	2.600			
Y1	5.700			
V2	10.700			



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